

2-Input AND Gate with Open Drain Output

MC74VHC1G09

The MC74VHC1G09 is an advanced high speed CMOS 2-input AND gate with open drain output fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The input structures provide protection when voltages up to 5.5 V are applied, regardless of the supply voltage. This allows the device to be used to interface 5 V circuits to 3 V circuits. Some output structures also provide protection when $V_{CC} = 0$ V and when the output voltage exceeds V_{CC} . These input and output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

Features

- Designed for 2.0 V to 5.5 V V_{CC} Operation
- 4.3 ns t_{PD} at 5 V (typ)
- Inputs/Outputs Over-Voltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 8 mA at 3.0 V
- Available in SC-88A, SC-74A, TSOP-5, SOT-553, SOT-953 and UDFN6 Packages
- Chip Complexity < 100 FETs
- -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

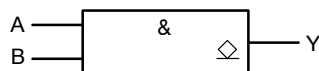
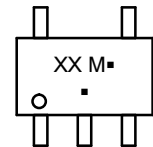


Figure 1. Logic Symbol

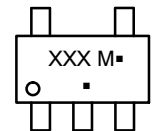
MARKING DIAGRAMS



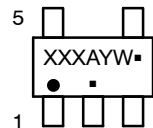
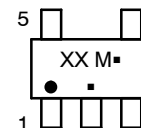
SC-88A
DF SUFFIX
CASE 419A



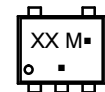
SC-74A
DBV SUFFIX
CASE 318BQ



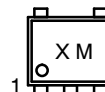
TSOP-5
DT SUFFIX
CASE 483



SOT-553
XV5 SUFFIX
CASE 463B



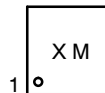
SOT-953
P5 SUFFIX
CASE 527AE



UDFN6
1.45 x 1.0
CASE 517AQ



UDFN6
1.0 x 1.0
CASE 517BX



XX = Specific Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

MC74VHC1G09

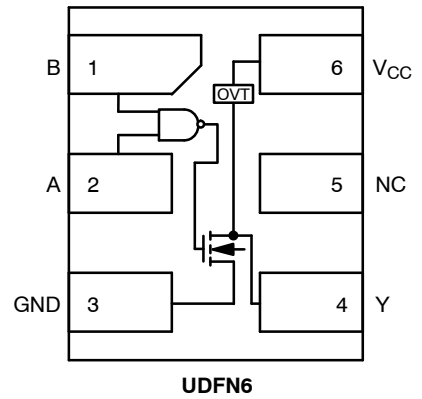
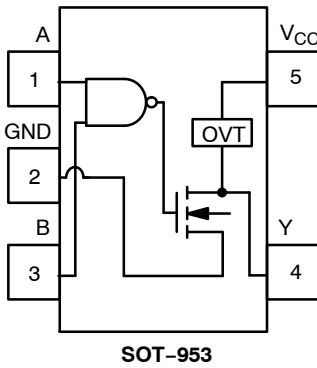
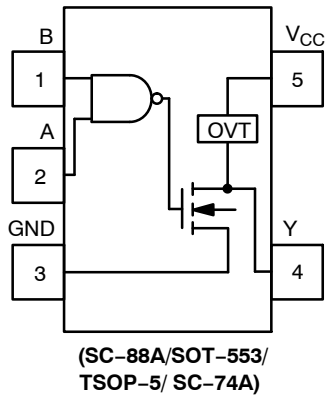


Figure 2. Pinout (Top View)

PIN ASSIGNMENT

(SC-88A/SOT-553/ TSOP-5/SC-74A)

| Pin | Function |
|-----|-----------------|
| 1 | B |
| 2 | A |
| 3 | GND |
| 4 | Y |
| 5 | V _{CC} |

PIN ASSIGNMENT (SOT-953)

| Pin | Function |
|-----|-----------------|
| 1 | A |
| 2 | GND |
| 3 | B |
| 4 | Y |
| 5 | V _{CC} |

PIN ASSIGNMENT (UDFN)

| Pin | Function |
|-----|-----------------|
| 1 | B |
| 2 | A |
| 3 | GND |
| 4 | Y |
| 5 | NC |
| 6 | V _{CC} |

FUNCTION TABLE

| Input | | Output |
|-------|---|--------|
| A | B | Y |
| L | L | L |
| L | H | L |
| H | L | L |
| H | H | Z |

MC74VHC1G09

MAXIMUM RATINGS

| Symbol | Characteristics | Value | Unit |
|-------------------------------------|--|---|------|
| V _{CC} | DC Supply Voltage | -0.5 to +6.5 | V |
| V _{IN} | DC Input Voltage | -0.5 to +6.5 | V |
| V _{OUT} | DC Output Voltage Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V) | -0.5 to V _{CC} + 0.5 -0.5 to +6.5 -0.5 to +6.5 | V |
| I _{IK} | DC Input Diode Current V _{IN} < GND | -20 | mA |
| I _{OK} | DC Output Diode Current V _{OUT} < GND | -20 | mA |
| I _{OUT} | DC Output Source/Sink Current | ±25 | mA |
| I _{CC} or I _{GND} | DC Supply Current per Supply Pin or Ground Pin | ±50 | mA |
| T _{STG} | Storage Temperature Range | -65 to +150 | °C |
| T _L | Lead Temperature, 1 mm from Case for 10 secs | 260 | °C |
| T _J | Junction Temperature Under Bias | +150 | °C |
| θ _{JA} | Thermal Resistance (Note 2) SC-88A SC-74A SOT-553 SOT-953 UDFN6 | 377 320 324 254 154 | °C/W |
| P _D | Power Dissipation in Still Air SC-88A SC-74A SOT-553 SOT-953 UDFN6 | 332 390 386 491 812 | mW |
| MSL | Moisture Sensitivity | Level 1 | - |
| F _R | Flammability Rating Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in | - |
| V _{ESD} | ESD Withstand Voltage (Note 3) Human Body Model Charged Device Model | 2000 1000 | V |
| I _{Latchup} | Latchup Performance (Note 4) | ± 100 | mA |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.
2. Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
3. HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Characteristics | Min | Max | Unit |
|---------------------------------|---|------------------|-------------------------------|------|
| V _{CC} | Positive DC Supply Voltage | 2.0 | 5.5 | V |
| V _{IN} | DC Input Voltage | 0 | 5.5 | V |
| V _{OUT} | DC Output Voltage Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V) | 0 0 0 | V _{CC} 5.5 5.5 | V |
| T _A | Operating Temperature Range | -55 | +125 | °C |
| t _r , t _f | Input Rise and Fall Time V _{CC} = 2.0 V V _{CC} = 2.3 V to 2.7 V V _{CC} = 3.0 V to 3.6 V V _{CC} = 4.5 V to 5.5 V | 0 0 0 0 | 20 20 10 5 | ns/V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

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DC ELECTRICAL CHARACTERISTICS (MC74VHC1G09)

| Symbol | Parameter | Test Conditions | V _{CC} (V) | T _A = 25°C | | | -40°C ≤ T _A ≤ 85°C | | -55°C ≤ T _A ≤ 125°C | | Unit |
|------------------|--------------------------------|---|---------------------|-----------------------|-----|-------|-------------------------------|------|--------------------------------|------|------|
| | | | | Min | Typ | Max | Min | Max | Min | Max | |
| V _{IH} | High-Level Input Voltage | | 2.0 | 1.5 | - | - | 1.5 | - | 1.5 | - | V |
| | | | 3.0 | 2.1 | - | - | 2.1 | - | 2.1 | - | |
| | | | 4.5 | 3.15 | - | - | 3.15 | - | 3.15 | - | |
| | | | 5.5 | 3.85 | - | - | 3.85 | - | 3.85 | - | |
| V _{IL} | Low-Level Input Voltage | | 2.0 | - | - | 0.5 | - | 0.5 | - | 0.5 | V |
| | | | 3.0 | - | - | 0.9 | - | 0.9 | - | 0.9 | |
| | | | 4.5 | - | - | 1.35 | - | 1.35 | - | 1.35 | |
| | | | 5.5 | - | - | 1.65 | - | 1.65 | - | 1.65 | |
| V _{OL} | Low-Level Output Voltage | V _{IN} = V _{IH} or V _{IL} I _{OL} = 50 μA I _{OL} = 50 μA I _{OL} = 50 μA I _{OL} = 4 mA I _{OL} = 8 mA | 2.0 | - | 0.0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | | 3.0 | - | 0.0 | 0.1 | - | 0.1 | - | 0.1 | |
| | | | 4.5 | - | 0.0 | 0.1 | - | 0.1 | - | 0.1 | |
| | | | 3.0 | - | - | 0.36 | - | 0.44 | - | 0.52 | |
| | | | 4.5 | - | - | 0.36 | - | 0.44 | - | 0.52 | |
| I _{IN} | Input Leakage Current | V _{IN} = 5.5 V or GND | 2.0 to 5.5 | - | - | ±0.1 | - | ±1.0 | - | ±1.0 | μA |
| I _{OZ} | 3-State Output Leakage Current | V _{OUT} = 0 V to 5.5 V | 5.5 | - | - | ±0.25 | - | ±2.5 | - | ±2.5 | μA |
| I _{OFF} | Power Off Leakage Current | V _{IN} = 5.5 V or V _{OUT} = 5.5 V | 0.0 | - | - | 1.0 | - | 10 | - | 10 | μA |
| I _{CC} | Quiescent Supply Current | V _{IN} = V _{CC} or GND | 5.5 | - | - | 1.0 | - | 20 | - | 40 | μA |

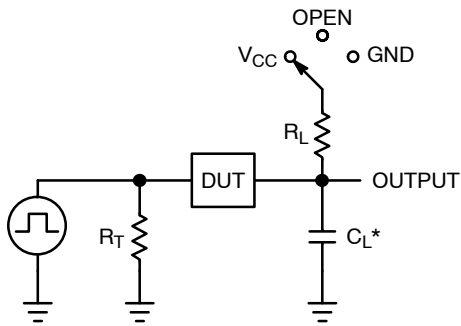
AC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Conditions | V _{CC} (V) | T _A = 25°C | | | -40°C ≤ T _A ≤ 85°C | | -55°C ≤ T _A ≤ 125°C | | Unit |
|------------------|--|--------------------------------|---------------------|-----------------------|-----|------|-------------------------------|------|--------------------------------|------|------|
| | | | | Min | Typ | Max | Min | Max | Min | Max | |
| t _{PZL} | Propagation Delay, (A or B) to Y (Figures 3 and 4) | C _L = 15 pF | 3.0 to 3.6 | - | 6.2 | 8.8 | - | 10.5 | - | 12.5 | ns |
| | | C _L = 50 pF | | - | 8.7 | 12.3 | - | 14.0 | - | 16.5 | |
| | | C _L = 15 pF | 4.5 to 5.5 | - | 4.3 | 5.9 | - | 7.0 | - | 9.0 | |
| | | C _L = 50 pF | | - | 5.8 | 7.9 | - | 9.0 | - | 11.0 | |
| t _{PLZ} | Propagation Delay, (A or B) to Y (Figures 3 and 4) | C _L = 15 pF | 3.0 to 3.6 | - | 6.5 | 9.7 | - | 11.5 | - | 14.5 | ns |
| | | C _L = 50 pF | | - | 8.7 | 12.3 | - | 14.0 | - | 16.5 | |
| | | C _L = 15 pF | 4.5 to 5.5 | - | 4.8 | 6.8 | - | 8.0 | - | 10.0 | |
| | | C _L = 50 pF | | - | 5.8 | 7.9 | - | 9.0 | - | 11.0 | |
| C _{IN} | Input Capacitance | | | - | 4.0 | 10 | - | 10 | - | 10 | pF |
| C _{OUT} | Output Capacitance | Output in High Impedance State | | - | 6.0 | - | - | - | - | - | pF |

| C _{PD} | Power Dissipation Capacitance (Note 5) | Typical @ 25°C, V _{CC} = 5.0 V | |
|-----------------|--|---|------|
| | | Value | Unit |
| | | 8.0 | pF |

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

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C_L includes probe and jig capacitance
 R_T is Z_{OUT} of pulse generator (typically 50 Ω)
 $f = 1$ MHz

Figure 3. Test Circuit

| Test | Switch Position | C_L , pF | R_L , Ω |
|---------------------|-----------------|------------------------------|------------------|
| t_{PLH} / t_{PHL} | Open | See AC Characteristics Table | X |
| t_{PLZ} / t_{PZL} | V_{CC} | | 1 k |
| t_{PHZ} / t_{PZH} | GND | | 1 k |

X = Don't Care

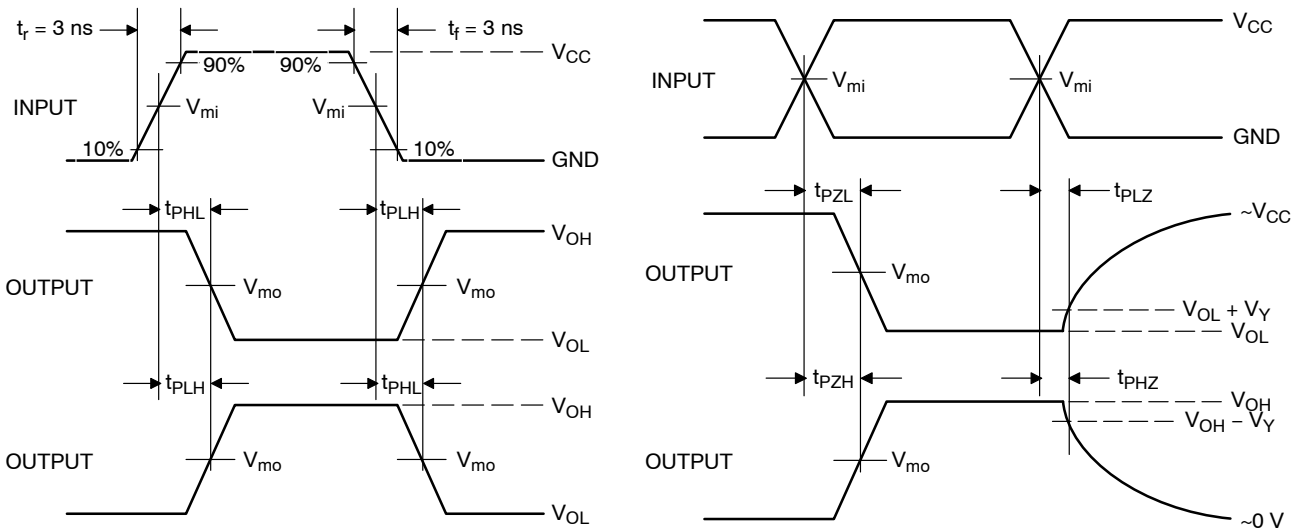


Figure 4. Switching Waveforms

| V_{CC} , V | V_{mi} , V | V_{mo} , V | | V_Y , V |
|--------------|--------------|-----------------------|---|-----------|
| | | t_{PLH} , t_{PHL} | t_{PZL} , t_{PLZ} , t_{PZH} , t_{PHZ} | |
| 3.0 to 3.6 | $V_{CC}/2$ | $V_{CC}/2$ | $V_{CC}/2$ | 0.3 |
| 4.5 to 5.5 | $V_{CC}/2$ | $V_{CC}/2$ | $V_{CC}/2$ | 0.3 |

MC74VHC1G09

ORDERING INFORMATION

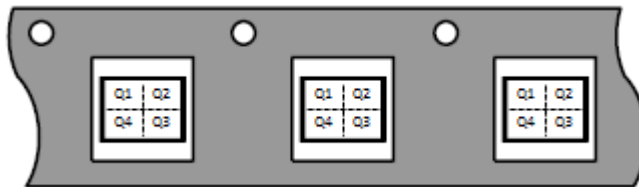
| Device | Packages | Specific Device Code | Pin 1 Orientation (See below) | Shipping [†] |
|---|----------------------------|----------------------|----------------------------------|-----------------------|
| MC74VHC1G09DFT1G | SC-88A | VX | Q2 | 3000 / Tape & Reel |
| MC74VHC1G09DFT2G | SC-88A | VX | Q4 | 3000 / Tape & Reel |
| MC74VHC1G09DFT1G-Q* (Please contact onsemi) | SC-88A | VX | Q2 | 3000 / Tape & Reel |
| MC74VHC1G09DFT2G-Q* (Please contact onsemi) | SC-88A | VX | Q4 | 3000 / Tape & Reel |
| MC74VHC1G09DBVT1G | SC-74A | VX | Q4 | 3000 / Tape & Reel |
| MC74VHC1G09DBVT1G-Q* (Please contact onsemi) | SC-74A | VX | Q4 | 3000 / Tape & Reel |
| MC74VHC1G09DTT1G-Q* (Please contact onsemi) | TSOP-5 | VX | Q4 | 3000 / Tape & Reel |
| MC74VHC1G09XV5T2G (Please contact onsemi) | SOT-553 | TBD | Q4 | 4000 / Tape & Reel |
| MC74VHC1G09P5T5G (Please contact onsemi) | SOT-953 | TBD | Q2 | 8000 / Tape & Reel |
| MC74VHC1G09MU1TCG (Please contact onsemi) | UDFN6, 1.45 x 1.0, 0.5P | TBD | Q4 | 3000 / Tape & Reel |
| MC74VHC1G09MU3TCG (Please contact onsemi) | UDFN6, 1.0 x 1.0, 0.35P | TBD | Q4 | 3000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

* -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

Pin 1 Orientation in Tape and Reel

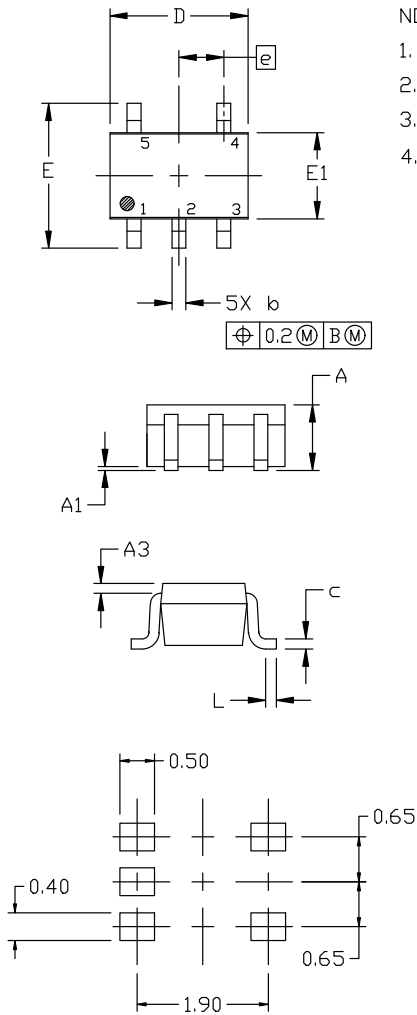
Direction of Feed



MC74VHC1G09

PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353)
CASE 419A-02
ISSUE M



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. 419A-01 OBSOLETE. NEW STANDARD 419A-02
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

| DIM | MILLIMETERS | | |
|-----|-------------|------|------|
| | MIN. | NOM. | MAX. |
| A | 0.80 | 0.95 | 1.10 |
| A1 | --- | --- | 0.10 |
| A3 | 0.20 REF | | |
| b | 0.10 | 0.20 | 0.30 |
| c | 0.10 | --- | 0.25 |
| D | 1.80 | 2.00 | 2.20 |
| E | 2.00 | 2.10 | 2.20 |
| E1 | 1.15 | 1.25 | 1.35 |
| e | 0.65 BSC | | |
| L | 0.10 | 0.15 | 0.30 |

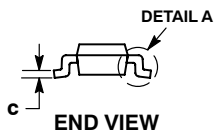
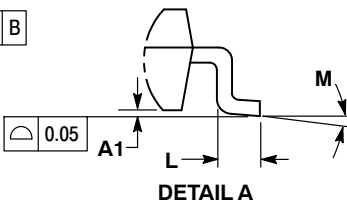
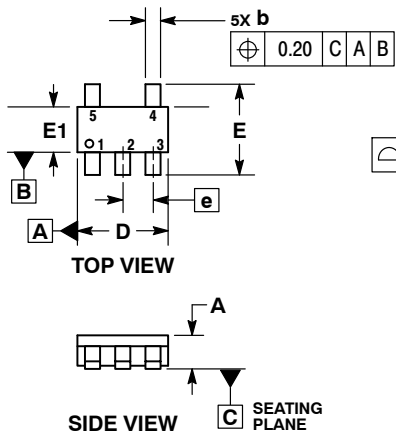
RECOMMENDED MOUNTING FOOTPRINT

- * For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

SC-74A
CASE 318BQ
ISSUE B

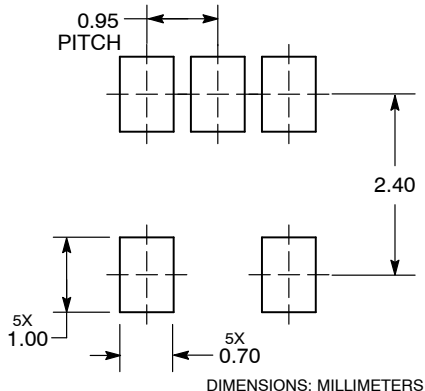


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 0.90 | 1.10 |
| A1 | 0.01 | 0.10 |
| b | 0.25 | 0.50 |
| c | 0.10 | 0.26 |
| D | 2.85 | 3.15 |
| E | 2.50 | 3.00 |
| E1 | 1.35 | 1.65 |
| e | 0.95 BSC | |
| L | 0.20 | 0.60 |
| M | 0° | 10° |

RECOMMENDED SOLDERING FOOTPRINT*



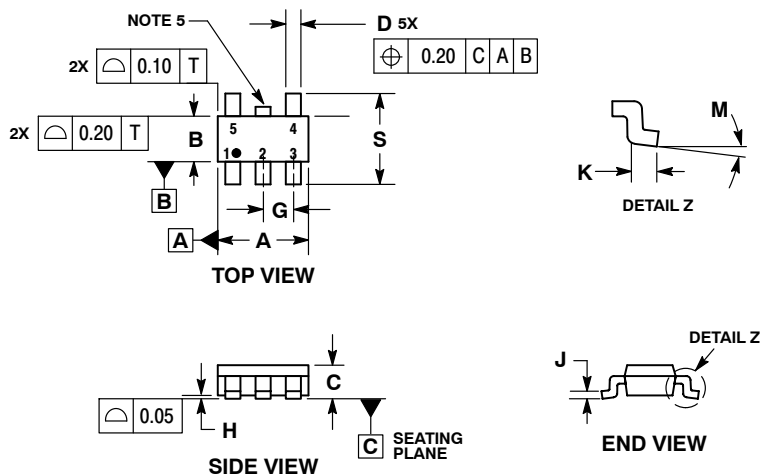
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74VHC1G09

PACKAGE DIMENSIONS

TSOP-5
CASE 483
ISSUE N

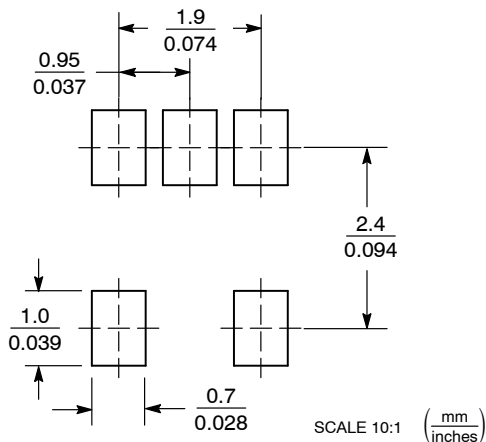


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 2.85 | 3.15 |
| B | 1.35 | 1.65 |
| C | 0.90 | 1.10 |
| D | 0.25 | 0.50 |
| G | 0.95 BSC | |
| H | 0.01 | 0.10 |
| J | 0.10 | 0.26 |
| K | 0.20 | 0.60 |
| M | 0° | 10° |
| S | 2.50 | 3.00 |

SOLDERING FOOTPRINT*

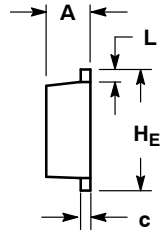
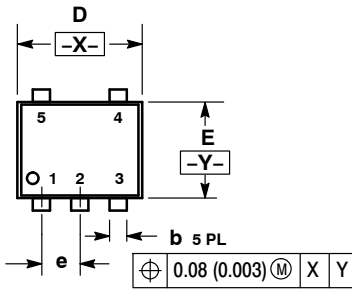


*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74VHC1G09

PACKAGE DIMENSIONS

SOT-553, 5 LEAD CASE 463B ISSUE C

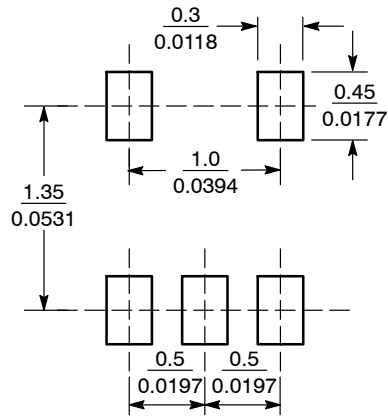


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.50 | 0.55 | 0.60 | 0.020 | 0.022 | 0.024 |
| b | 0.17 | 0.22 | 0.27 | 0.007 | 0.009 | 0.011 |
| c | 0.08 | 0.13 | 0.18 | 0.003 | 0.005 | 0.007 |
| D | 1.55 | 1.60 | 1.65 | 0.061 | 0.063 | 0.065 |
| E | 1.15 | 1.20 | 1.25 | 0.045 | 0.047 | 0.049 |
| e | 0.50 BSC | | | 0.020 BSC | | |
| L | 0.10 | 0.20 | 0.30 | 0.004 | 0.008 | 0.012 |
| HE | 1.55 | 1.60 | 1.65 | 0.061 | 0.063 | 0.065 |

RECOMMENDED SOLDERING FOOTPRINT*



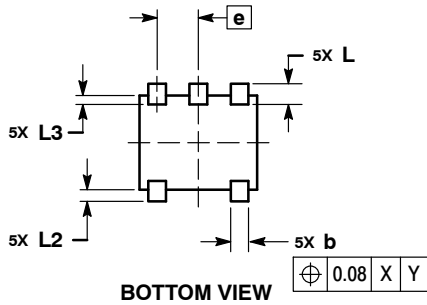
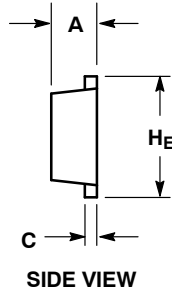
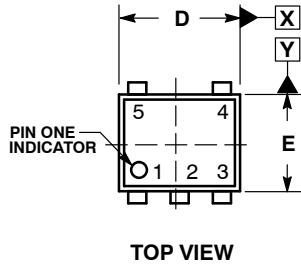
SCALE 20:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74VHC1G09

PACKAGE DIMENSIONS

SOT-953
CASE 527AE
ISSUE E

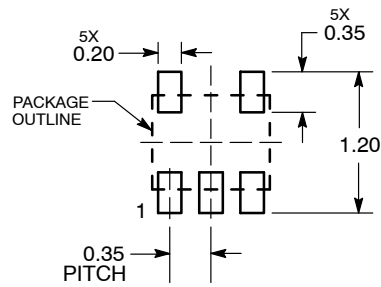


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| MILLIMETERS | | | |
|----------------|-----------|------|------|
| DIM | MIN | NOM | MAX |
| A | 0.34 | 0.37 | 0.40 |
| b | 0.10 | 0.15 | 0.20 |
| C | 0.07 | 0.12 | 0.17 |
| D | 0.95 | 1.00 | 1.05 |
| E | 0.75 | 0.80 | 0.85 |
| e | 0.35 BSC | | |
| H _E | 0.95 | 1.00 | 1.05 |
| L | 0.175 REF | | |
| L2 | 0.05 | 0.10 | 0.15 |
| L3 | --- | --- | 0.15 |

SOLDERING FOOTPRINT*



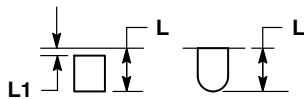
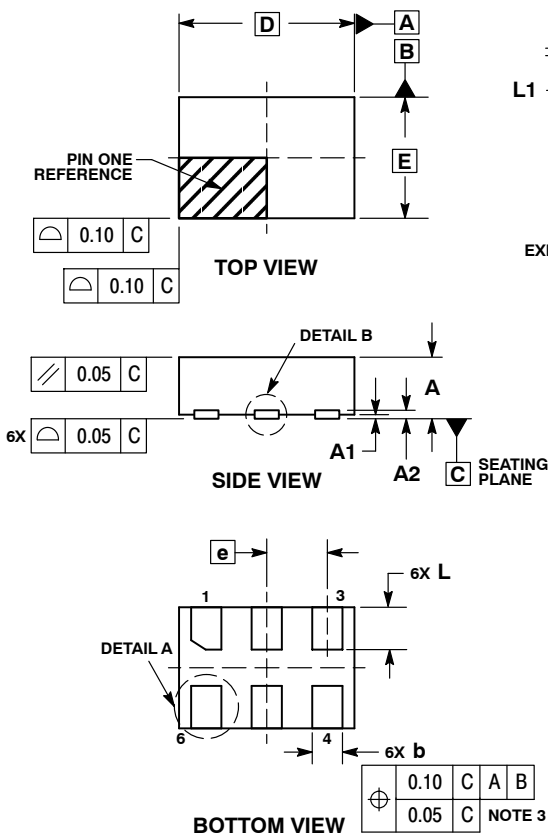
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74VHC1G09

PACKAGE DIMENSIONS

UDFN6, 1.45x1.0, 0.5P
CASE 517AQ
ISSUE O



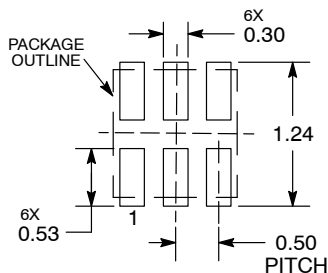
EXPOSED Cu MOLD CMPD

DETAIL B
OPTIONAL CONSTRUCTIONS

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

| MILLIMETERS | | |
|-------------|----------|------|
| DIM | MIN | MAX |
| A | 0.45 | 0.55 |
| A1 | 0.00 | 0.05 |
| A2 | 0.07 REF | |
| b | 0.20 | 0.30 |
| D | 1.45 BSC | |
| E | 1.00 BSC | |
| e | 0.50 BSC | |
| L | 0.30 | 0.40 |
| L1 | --- | 0.15 |

MOUNTING FOOTPRINT



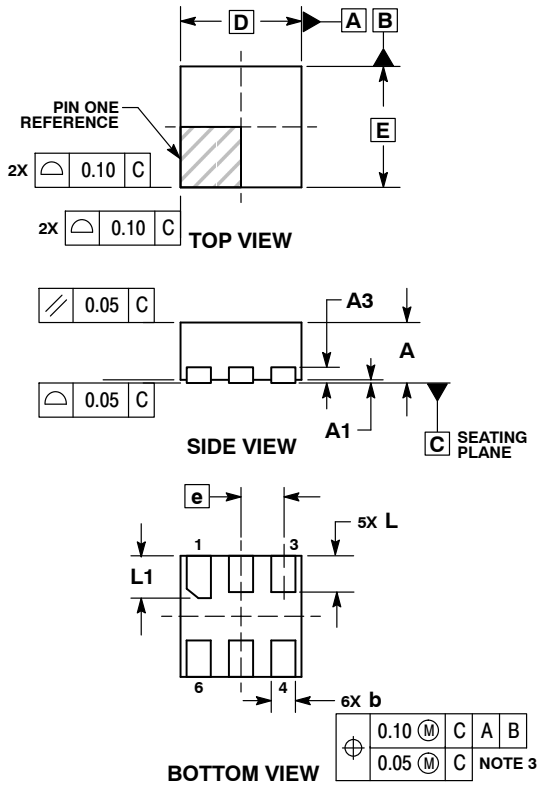
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74VHC1G09

PACKAGE DIMENSIONS

UDFN6, 1x1, 0.35P
CASE 517BX
ISSUE O

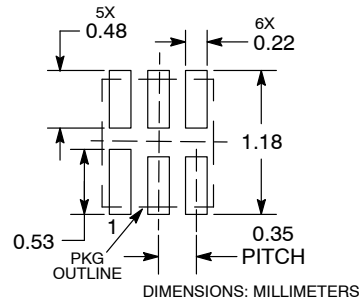


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 0.45 | 0.55 |
| A1 | 0.00 | 0.05 |
| A3 | 0.13 REF | |
| b | 0.12 | 0.22 |
| D | 1.00 BSC | |
| E | 1.00 BSC | |
| e | 0.35 BSC | |
| L | 0.25 | 0.35 |
| L1 | 0.30 | 0.40 |

RECOMMENDED SOLDERING FOOTPRINT*



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